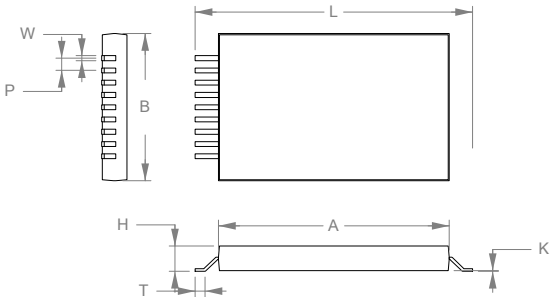


Component (Fig. 1)

Small Outline IC (SOIC)	
Pitch.....	1.00
Pin Package.....	18
Pin Count.....	9
Lmin.....	22.60
Lmax.....	22.60
Tmin.....	0.80
Tmax.....	0.80
Wmin.....	0.40
Wmax.....	0.40
Amin.....	18.80
Amax.....	18.80
Bmin.....	12.00
Bmax.....	12.00
Hmax.....	2.04
Kmin.....	0.05

Fig.1



Solder Joint Goals (Fig. 2)

Environment is C - LEAST

Toe (Outside) Goal.....	0.15
Toe min.....	0.15
Toe max.....	0.23
Heel (Inside) Goal.....	0.25
Heel Min.....	0.25
Heel max.....	0.33
Side Goal.....	0.01
Side Min.....	0.00
Side max.....	0.08

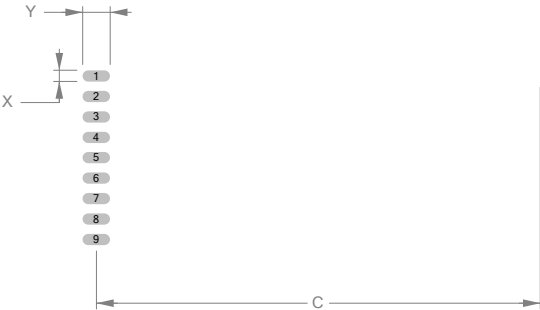
Fig.2



Land Pattern (Fig. 3)

C.....	21.70
Y.....	1.35
X.....	0.55
Pin(s) default	
b135_55	

Fig.3



Silkscreen (Fig. 4)

R1.....19.70  
R2.....12.00

Assembly (Fig. 5)

Anom.....18.80  
Bnom.....12.00

Courtyard (Fig. 6)

V1.....23.30  
V2.....12.20

Program Version: 2010.00.00

Advisories

None

Fig.4

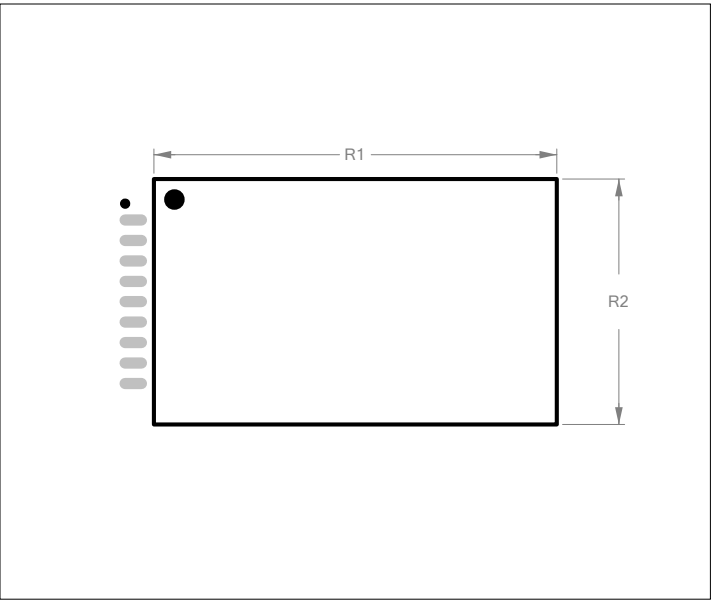


Fig.5

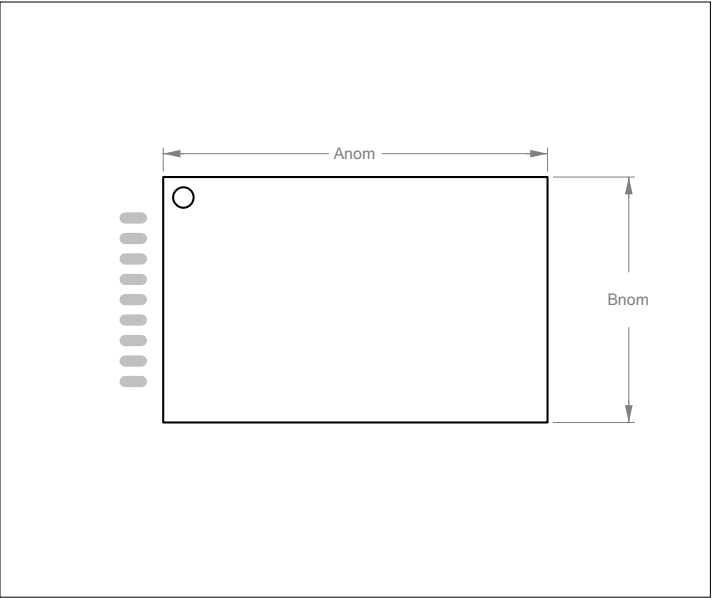


Fig.6

